

## 1. General description

Silicon Carbide Schottky diode (Bare Die).

## 2. Features and benefits

- Extremely fast reverse recovery time
- Low figure of merit ( $Q_r \cdot V_F$ )
- Highly stable switching performance
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RRM}^*$	repetitive peak reverse voltage		-	-	1200	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$ ; square-wave pulse	-	-	15	A
<b>Static characteristics</b>						
$V_F^{**}$	forward voltage	$I_F = 15\text{ A}; T_j = 25\text{ °C}$	-	1.45	1.7	V
		$I_F = 15\text{ A}; T_j = 150\text{ °C}$	-	1.95	2.3	V
<b>Dynamic characteristics</b>						
$Q_r^{**}$	recovered charge	$I_F = 15\text{ A}; V_R = 400\text{ V}; dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 25\text{ °C}$	-	35	-	nC

## 4. Ordering information

Table 2. Ordering information

Type number	Orderable part number	Name	Description	Version
WB15SC120AL	WB15SC120ALZ	Wafer	Bare die on wafer	Die

## 5. Limiting values

**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}^*$	repetitive peak reverse voltage		-	1200	V
$V_{RWM}^*$	crest working reverse voltage		-	1200	V
$V_R^*$	reverse voltage	DC	-	1200	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$ ; square-wave pulse	-	15	A
$I_{FRM}^{**}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25 \mu s$ ; square-wave pulse	-	30	A
$I_{FSM}^{**}$	non-repetitive peak forward current	$t_p = 10 ms$ ; $T_{j(init)} = 25 \text{ }^\circ\text{C}$ ; sine-wave pulse	-	102	A
		$t_p = 10 \mu s$ ; $T_{j(init)} = 25 \text{ }^\circ\text{C}$ ; square-wave pulse	-	950	A
$T_{stg}^{**}$	storage temperature		-55	175	$^\circ\text{C}$
$T_j^{**}$	junction temperature		-	175	$^\circ\text{C}$

## 6. Characteristics

Table 4. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F^*$	forward voltage	$I_F = 15 \text{ A}; T_J = 25 \text{ }^\circ\text{C}$	-	1.45	1.7	V
$V_F^{**}$	forward voltage	$I_F = 15 \text{ A}; T_J = 150 \text{ }^\circ\text{C}$	-	1.95	2.3	V
$I_R^*$	reverse current	$V_R = 1200 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	5	150	$\mu\text{A}$
$I_R^{**}$	reverse current	$V_R = 1200 \text{ V}; T_J = 150 \text{ }^\circ\text{C}$	-	80	-	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r^{**}$	recovered charge	$I_F = 15 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A}/\mu\text{s}; T_J = 25 \text{ }^\circ\text{C}$	-	35	-	nC
$C_d^{**}$	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	700	-	pF
		$f = 1 \text{ MHz}; V_R = 400 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	65	-	pF
		$f = 1 \text{ MHz}; V_R = 800 \text{ V}; T_J = 25 \text{ }^\circ\text{C}$	-	48	-	pF

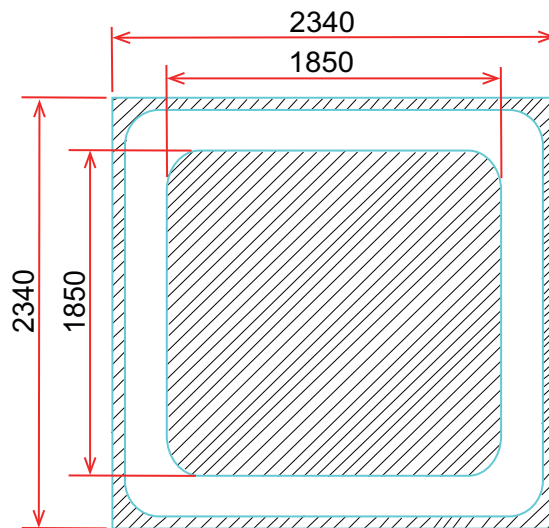
Notes:

(1) \* mean that parameter are 100% test at  $T_{amb} = 25^\circ\text{C}$

(2) \*\* means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet, similar to the assembled devices like WNSC2D151200W.

MECHANICAL SPECIFICATIONS		
Chip size	2.34 x 2.34	mm <sup>2</sup>
Anode pad size	1.85 x 1.85	mm <sup>2</sup>
Scribe line width	80	µm
Area total / active	5.48 / 3.42	mm <sup>2</sup>
Thickness	165	µm
Wafer size	100	mm
Max possible chips per wafer	1280	pcs
Passivation	Polyimide	
Front metal	AlCu	
Back metal	Ti Ni Ag	

**CHIP LAYOUT**



**Die size: 2340µm x 2340µm**  
**Bond pad size: 1850µm x 1850µm**

## 7. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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